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To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

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	(1)	Mitsutoshi HIGASHI		(2)	Niroko KOIKE				
2.	Name and address of receiving party(ies):								
	711, Az	O ELECTRIC INDUSTRIES (za Shariden, Oaza Kurita o-shi, Nagano 380-0921 JAF	·			122850 122850			
3.	Nature of conveyance:								
	<u>x</u> 	Assignment Security Agreement Other:		Merge Chang	r e of Name -	of S			
	Execution Date	(s): October 13, 1999	_		- 4 5 -				
4.	Application number(s) or patent number(s): 09/42285								
	(a) The exc (b) The title *** OR This document	is being filed together with a ecution date(s) of the applica is: SEMICONDUCTOR DE *** is being filed after filing of the Application No(s)/ No(s), issued	tion is/are: VICE MOD application	October ULE AN	D A PART THEREOF				
_									
5.	Name and address of party to whom correspondence concerning document should be mailed: STAAS & HALSEY LLP Our Docket: 300.1082/HJS								
	Attention: H. J. Staas 700 Eleventh Street, N.W., Suite 500 Washington, D.C. 20001								
6.	Total number of applications and patents involved:1_								
7.	Total fee (37 CFR 3.41) \$ 40.00								
	<u>X</u>	Enclosed Authorized to be charged to	deposit acc	count.					
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	To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.								
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PATENT REEL: 010352 FRAME: 0246

U.S. ASSIGNMENT

IN CONSIDERATION of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned inventor(s) (hereinafter "ASSIGNOR") by

(Insert	SHINKO ELECTRIC IND	OUSTRIES CO., LTD.						
ASSIGNEE's Name(s) Address(es))	711, Aza Shariden,	Oaza Kurita, Nagano-shi	, Nagano 380-0921, Jap	oan				
Title of invention)	(hereinafter "ASSIGNEE"), the receipt of which is hereby acknowledged, the undersigned ASSIGNOR hereby sells, assigns a transfers to ASSIGNEE the entire and exclusive right, title and interest to the invention entitled SEMICONDUCTOR DEVICE MODULE AND A PART THEREOF							
	relating to International Patent Application PCT/JP/ and/or for which application for Letters Pate of the United States was executed on even date herewith or, if not so executed, was:							
nsert date f execution f application,	(a) executed on	,) is he	reby authorized to insert in (b) the s	pecified				
not oncurrent)	Senai No/	data, when known.						
	producing evidence.	declarations, taking all rightful oaths, pr						
(Signatures)	1) Mitantochi Higoshi (SIGNATURE)	Mitsutoshi Higashi	October 13, 1999					
	(SIGNATURE)	(TYPE NAME)	(DATE)					
	a Hiroto Koike	Hiroko Koike	October 13, 1999					
	(SIGNATURE)	(TYPE NAME)	(DATE)					
	3)(SIGNATURE)	(TYPE NAME)	(DATE)					
	4)(SIGNATURE)	(TYPE NAME)	(DATE)					
	5)(SIGNATURE)	(TYPE NAME)	(DATE)					
	6)(SIGNATURE)	(TYPE NAME)	(DATE)					
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